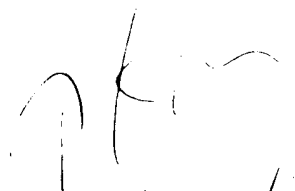


	L #	Hits	Search Text
1	L1	789	(wafer or substrate) with (dice or dicing) with (scrib\$3)
2	L2	291182	(imag\$3 near3 (device or apparatus or system)) or camera or CCD
3	L3	149	1 and 2
4	L4	106	(camera or CCD) and 1
5	L5	24	(coordinat\$3) near4 (scribe near2 line)
6	L6	1	4 and 5
7	L7	62	(coordinat\$3) with (scrib\$3 near2 line)
8	L8	1	4 and 7
9	L9	136	(coordinat\$3) with (scrib\$3)
10	L10	1	4 and 9
11	L11	85433	(heat\$3) near5 (wafer or substrate)
12	L12	27	4 and 11

	L #	Hits	Search Text
13	L13	97	(camera) and 1
14	L14	74	13 not 12
15	L15	1	(x-ray or ultrasound) and 14
16	L16	1	15 and 1
17	L17	47	(x-ray or ultrasound) and 1
18	L18	6	(ultrasound) and 1
19	L19	1033	(ultrasound) same (wafer or substrate)
20	L20	31	(ultrasound) same (wafer or substrate) same (dic\$3 or scrib\$3)
21	L21	1	(ultrasound with imag\$3) and ((wafer or substrate) with (dic\$3 and scrib\$3))
22	L22	6	(ultrasound with imag\$3) and ((wafer or substrate) same (dic\$3 and scrib\$3))

  
 2/22/03